



**COUNCIL OF
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COVER NOTE

From:	Secretary-General of the European Commission, signed by Mr Jordi AYET PUIGARNAU, Director
date of receipt:	14 March 2014
To:	Mr Uwe CORSEPIUS, Secretary-General of the Council of the European Union

No. Cion doc.:	C(2014) 1642 final - Annex 1
Subject:	Annex to the Commission Delegated Directive amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements

Delegations will find attached document C(2014) 1642 final - Annex 1.

Encl.: C(2014) 1642 final - Annex 1



EUROPEAN
COMMISSION

Brussels, 13.3.2014
C(2014) 1642 final

ANNEX 1

ANNEX

to the

Commission Delegated Directive

amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements.

ANNEX

to the

Commission Delegated Directive

amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements.

In Annex IV to Directive 2011/65/EU the following point 38 is added:

"38. Lead in solder in one interface of large area stacked die elements with more than 500 interconnects per interface which are used in X-ray detectors of computed tomography and X-ray systems

Expires on 31 December 2019. May be used after that date in spare parts for CT and X-ray systems placed on the market before 1 January 2020."